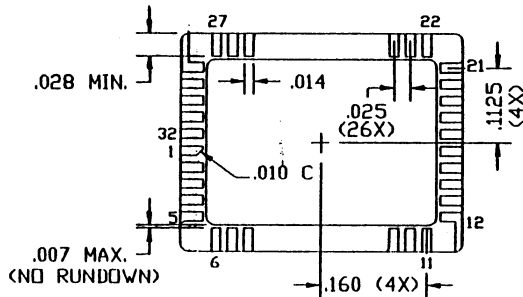
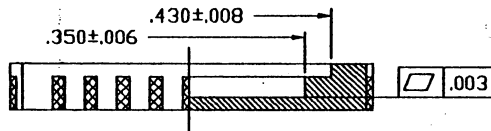
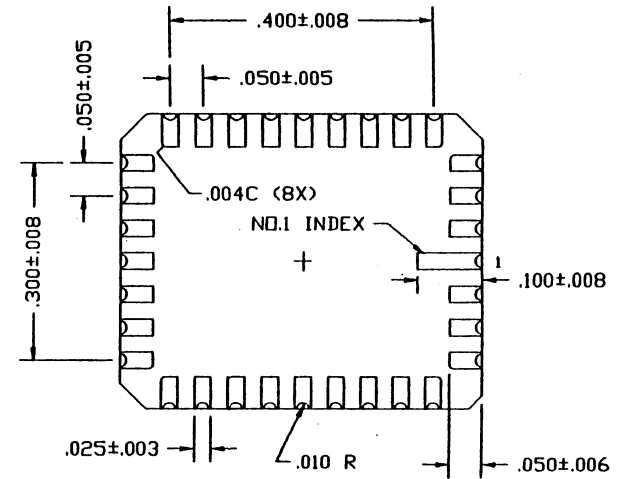
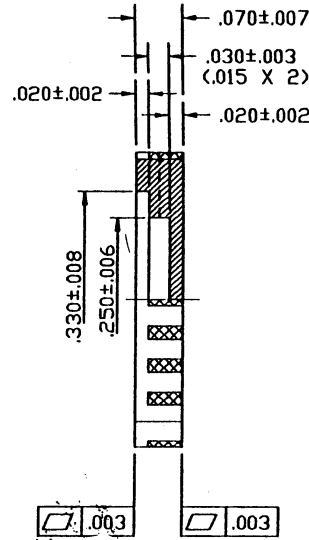
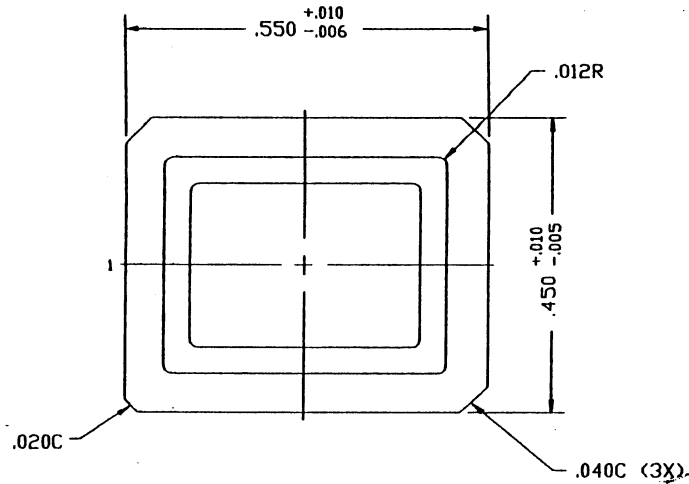


REVISIONS

ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
	**	49188	NEW RELEASE	03/11/97	



NOTES:

1. GOLD PLATE 80 u INCHES MIN. OVER
80 u INCHES MIN. NICKEL.
2. SEAL RING AND DIE ATTACH PAD ARE ISOLATED.
3. LEAD RESISTANCE _____ 250 mΩ MAX.
4. ALL PARTS SHALL CONFORM TO CYPRESS SEMICONDUCTOR SPECIFICATION NO. 03-00027

UNLESS OTHERWISE SPECIFIED		DESIGNED BY	DATE	TITLE		
ALL DIMENSIONS ARE IN INCHES STANDARD TOLERANCES IN		DRAWN	DATE	32 R LCC 250 X 350		
DECIMALS	ANGLES	HTN	03/11/97	SIZE	PART NO.	DWG NO.
.XX ± .01	± 0°30'	CHK BY	DATE	B	LCC32R30	51-20266
.XXX ± .005		APPROVED BY	DATE	SCALE		REV
.XXXX ± .001			3/11/97	5 X		**
MATERIAL	SEE NOTE	APPROVED BY	DATE			SHEET 1 OF 1
FINISH						

THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPE.
THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS
MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT

IRK 32F1-6100A LCC03248